

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A manufacturing method for a three-dimensional ~~structural body, photonic crystal~~, comprising:
 - A. holding, by a first holding member, a first cross-sectional form member from amongst a plurality of cross-sectional form members above a ~~first-substrate; substrate, a pattern member comprising the first holding member and the first cross-sectional form member;~~
 - B. first bonding/transferring and laminating the first cross-sectional form member onto a second substrate;
 - C. releasing the first cross-sectional form member from the first holding member after the first bonding/transferring and laminating;
 - D. holding, by a second holding member, a second cross-sectional form member from amongst the plurality of cross-sectional form members above the first substrate;
 - E. second bonding/transferring and laminating the second cross-sectional form member onto the first cross-sectional form member;
 - F. releasing the second cross-sectional form member from the second holding member after the second bonding/transferring and laminating;

repeating ~~Repeating~~ steps D, E and F, at least once, wherein, for each repetition, the "second holding member" becomes a new holding member and "~~second the~~ "second cross-sectional form member" becomes a new cross-sectional form member from amongst the plurality of cross-sectional form members and the "first cross-sectional form member" becomes the second cross-sectional form member from a previous repetition, respectively, wherein

each cross-sectional form member corresponds to a slice pattern of the three-dimensional ~~structural body~~ photonic crystal,

each cross-sectional form member comprises a plurality of longitudinal members separated by gaps from each other, each of the plurality of longitudinal members having two tips, one tip being connected to a lateral member, and the other tip being connected to another lateral member.

2. (Previously Presented) The manufacturing method according to claim 1, wherein the first or second bonding/transferring and laminating is performed using surface-activated bonding.

3. (Previously Presented) The manufacturing method according to claim 1, wherein the first or second holding member comprises a coupling member connected to a cross-sectional form member, and a frame member, wherein the first substrate is connected to the coupling member through the frame member.

4. (Original) The manufacturing method according to claim 3, wherein the frame member includes a columnar part provided on the first substrate, and a frame part provided on the columnar part and connected to the coupling member.

5. (Previously Presented) The manufacturing method according to claim 4, further comprising:

laminating a sacrificial layer and a material layer on the first substrate;

forming the cross-sectional form members, the frame part and the coupling member in the material layer; and

removing the sacrificial layer while a portion becoming the columnar part remains, and a gap occurs at least between the cross-sectional form members and the first substrate.

6. (Previously Presented) The manufacturing method according to claim 5, wherein the plurality of cross-sectional form members are formed by using a lithography method.

7. (Original) The manufacturing method according to claim 5, wherein the sacrificial layer is removed by using an under etching method.

8. (Previously Presented) The manufacturing method according to claim 3, wherein the coupling member is ruptured at a time of the first or second bonding/transferring and laminating.

9. (Currently Amended) The manufacturing method according to claim 1, further comprising a collective of one or more cross-sectional form members, wherein

_____ the first or second bonding/transferring and laminating is performed by causing the collective of cross-sectional form members to face the second substrate, and by sandwiching the collective of cross-sectional form members between the first substrate and the second ~~substrate, substrate, and~~

_____ the collective comprises a plurality of cross-sectional form members connected by a lateral member so that the longitudinal members extend along a substantially same direction.

10. (Currently Amended) The manufacturing method according to claim 3, further comprising a collective of one or more cross-sectional form members, wherein

_____ the first or second bonding/transferring and laminating is performed by causing the collective of cross-sectional form members to face the second substrate, and by sandwiching the collective of cross-sectional form members between the first substrate and the second ~~substrate, and substrate,~~

the coupling member is ruptured after the collective of cross-sectional form members are transferred on the second substrate and when the second substrate is separated from the first ~~substrate, substrate, and~~

the collective comprises a plurality of cross-sectional form members connected by a lateral member so that the longitudinal members extend along a substantially same direction.

11. (Previously Presented) The manufacturing method according to claim 9, wherein a surface on the first substrate facing the collective of cross-sectional form members is flat.

12. (Previously Presented) The manufacturing method according to claim 10, wherein a surface on the first substrate facing the collective of cross-sectional form members is flat.

13. (Previously Presented) The manufacturing method according to claim 9, wherein a pressure to sandwich the collective of cross-sectional form members between the first substrate and the second substrate is applied to all of the cross-sectional form members of the collective.

14. (Previously Presented) The manufacturing method according to claim 10, wherein a pressure to sandwich the collective of cross-sectional form members between the first substrate and the second substrate is applied to all of the cross-sectional form members of the collective.

15. (Previously Presented) The manufacturing method according to claim 1, wherein the first or second holding member comprises a first frame member positioned on the first substrate, a second frame member provided inside of the first frame member, a first coupling member connected to a cross-sectional form member, and a second coupling member connecting the first and the second frame members.

16. (Previously Presented) The manufacturing method according to claim 15, wherein the second frame member and a plurality of cross-sectional form members connected

to the second frame member are simultaneously bonded and transferred onto the second substrate.

17. (Previously Presented) The manufacturing method according to claim 16, wherein the first and second bonding/transferring and laminating is performed by causing the second substrate and the plurality of cross-sectional form members connected to the second frame member to face each other, and by sandwiching the second frame member and the plurality of cross-sectional form members between the first substrate and the second substrate.

18. (Original) The manufacturing method according to claim 1, wherein the three-dimensional structural body includes a photonic crystal having a periodic structure.

19. (New) A manufacturing method for a three-dimensional structural body, comprising:

sequentially bonding/transferring and laminating a plurality of cross-sectional form members onto a second substrate, each cross-sectional form member being held in space above a first substrate by a holding member; and

releasing the cross-sectional form member from the holding member after the bonding/transferring and laminating, wherein

the bonding/transferring and laminating is performed using surface-activated bonding.

20. (New) A manufacturing method for a three-dimensional structural body, comprising:

sequentially bonding/transferring and laminating a plurality of cross-sectional form members onto a second substrate, each cross-sectional form member being held in space above a first substrate by a holding member; and

releasing the cross-sectional form member from the holding member after the bonding/transferring and laminating, wherein

the holding member comprises a coupling member connected to a cross-sectional form member, and a frame member, wherein

the first substrate is connected to the coupling member through the frame member, wherein

the frame member includes a columnar part provided on the first substrate, and a frame part provided on the columnar part and connected to the coupling member;

the manufacturing method further comprising:

laminating a sacrificial layer and a material layer on the first substrate;

forming the cross-sectional form members, the frame part and the coupling member in the material layer; and

removing the sacrificial layer while a portion becoming the columnar part remains, and a gap occurs at least between the cross-sectional form members and the first substrate.